

TS98-574

Serial number 09/310,256

AMENDMENTS

IN THE CLAIMS

Please amend claim 1 as follows:

1. (Amended) Providing a method of reducing dry-etch cleaning chamber particle count at the end of power-down for said dry-etch chamber, comprising:

providing a dry-etch cleaning chamber, said dry-etch cleaning chamber having been provided with an Inductive Coupled Plasma (ICP) coil;

positioning a workpiece within said cleaning chamber; and

following a dry-etch chamber power-down procedure whereby said power-down is applied in a controlled and gradual manner, assuring reduced chamber particle count at the end of power-down of the dry-etch cleaning chamber.

REMARKS

Examiner S. Ahmed is thanked for thoroughly examining the Prior Art.

Favorable reconsideration of this application in light of the above amendments and the following remarks is respectfully requested.